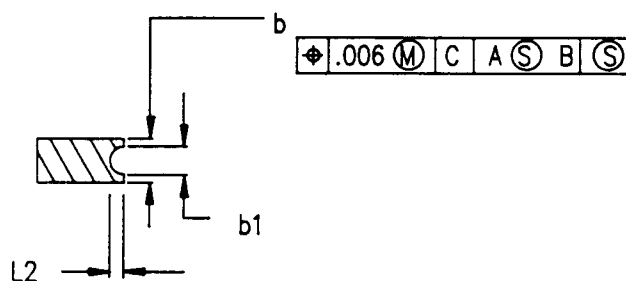
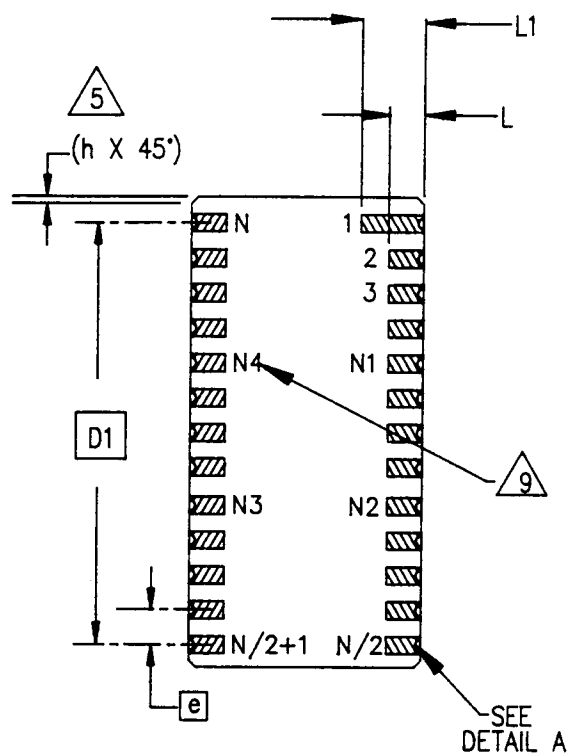
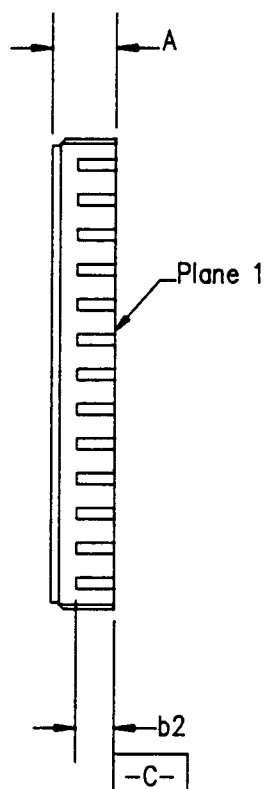
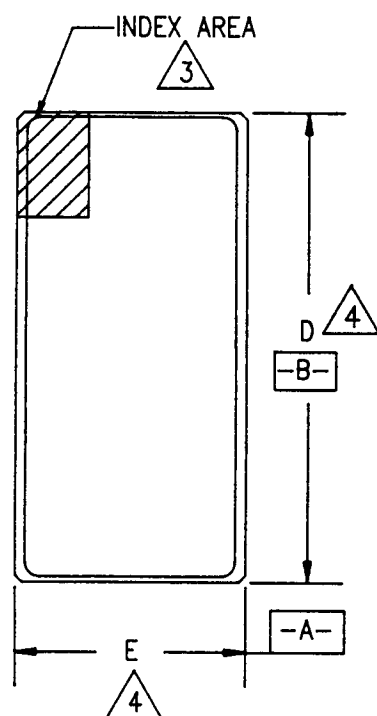


INCH



◆ .006 (M) C A (S) B (S)

DETAIL A

JEDEC
SOLID STATE
PRODUCT OUTLINE

TITLE: R-CDCC-N
LEADLESS SMALL OUTLINE
CERAMIC CHIP CARRIER
.350" BODY, .050" PITCH

ISSUE:
A

DATE:
JUNE
1993

M0-144

SHEET:
1 of 2

VARIATIONS
ALL DIMENSIONS SHOWN IN INCHES

INCH

SYMBOL	AA			NOTE
	MIN	NOM	MAX	
A	.060	.070	.080	
b	.022	.025	.028	
b1	.006	.014	.022	2
b2	.030	----	----	7
D	.665	.675	.685	4
D1	.600 BSC			
E	.340	.350	.360	4
e	.050 BSC			
h	.012 REF			5
L	.045	.050	.055	
L1	.080	.090	.100	
L2	.003	.009	.015	2
N	26			6
N1	5			9
N2	9			9
N3	18			9
N4	22			9
NOTE	1, 3, 8			
REF	10-319			
ISSUE	A			

NOTES:

1. All dimensions and tolerances conform to ANSI Y14.5M-1982.
2. Metallized castellations shall be connected to Plane 1 terminals.
3. 3. Index Area: An identification mark shall be located adjacent to pin one within the shaded area shown. Plane 1 terminal identification may be an extension of the length of the metallized terminal which shall not be wider than the b dimension.
4. 4. The cover shall not extend beyond the edges of the body.
5. 5. The corner shape (square, notch, radius, etc.) may vary at the manufacturer's option.
6. N indicates total number of terminal positions.
7. Unless otherwise specified, a minimum clearance of .015 inch shall be maintained between all metallized features (e.g., lid, castellation, terminals, thermal pads, etc.).
8. Solder finish is optional with a maximum allowable thickness of .007 inch. Measurement of dimensions A, b1, and L2 may be made prior to solder application.
9. 9. For terminal identification purposes only. Terminals between N1 and N2, and between N3 and N4 are omitted if values for, N1, N2, N3 and N4 are listed on the table.

JEDEC
SOLID STATE
PRODUCT OUTLINE

TITLE: R-CDCC-N
LEADLESS SMALL OUTLINE
CERAMIC CHIP CARRIER
.350" BODY, .050" PITCH

ISSUE:

A

DATE:

JUNE
1993

SHEET:

MO-144

2 OF 2